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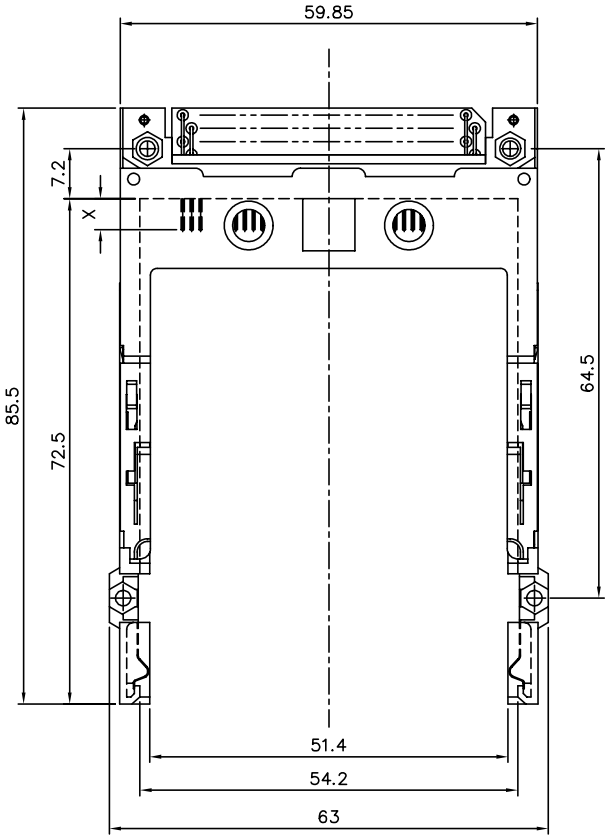
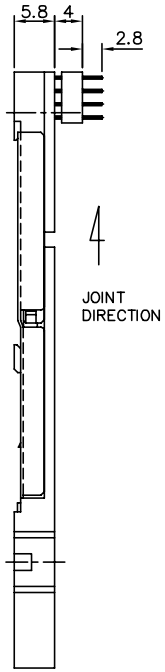
PRODUCT NO.
74500-040
74500-040LF



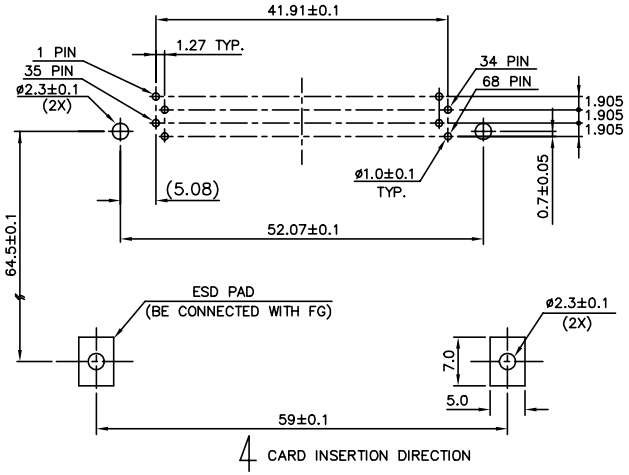


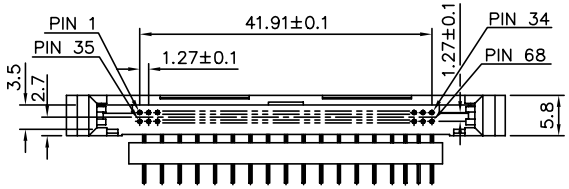
NOTES:
1. EJECT FORCE : 3.5 Kg MAX.
2. EJECT TRAVEL: 8.0mm
3. MATERIAL
   3.1 HEADER ASS'Y :
   HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
   PIN : COPPER ALLOY
   3.2 EJECT MECHANISM ASS'Y :
   HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK
   PLATE : STAINLESS
   EMI CONTACT: PHOSPHOR BRONZE
4. FINISH (PIN)
   UNDER PLATING : 0.5μm MIN. Ni
   CONTACT AREA : 0.076 μm MIN. GOLD

   SOLDER TAIL : 2.5μm MIN. Sn-Pb(FOR TIN LEAD OPTION)
   : 2.5μm MIN. PURE TIN (FOR LEAD FREE OPTION)
5.

DIM"X"	4.25±0.1	3.5±0.1	5.0±0.1
PIN MUMBER	OTHERS	36,67	1,17,34,35,51,68

6. IF LEAD FREE P.N.THE HOUSING WILL WITHSTAND EXPOSURE TO PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER 260°C APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
7. IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
8. LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
9. PRODUCT SPEC: 110-263





mat'l. code				surface	tolerance	projection	product family
				ISO1302 ✓	ISO406 ISO1101		PCMCIA
ltr	ecn no	dr	date	tolerances unless otherwise specified			title
A	T70405	WL	0923/97	angle	linear 0.X±0.3	MM	EJECTOR HEADER ASS'Y
B	T80096	WL	02/17/98		0.XX±0.13		68POS. R/A TYP 1/2/3
C	T03-0326	WL	08/14/03	0°±2°	0.XXX±0.05	scale 1.6:1	
D	N05-0127	WB	05/11/05	dr	WENDY.CHEN	07/30/97	dwg no 74500 sheet 1 of 2 size A4
E	ELX-N-007947	ZK	11/01/11	engr	JOSPH HSIA	07/30/97	
F	ELX-N-011420	ZK	04/07/12	chr	JOSEPH HSIA	07/30/97	
				appd	JENN TSAO	07/30/97	type Product Customer Drawing
sheet index	revision	F	F				
	sheet	1	2				

form: A4mmXLc

PDS: Rev :F STATUS:Released Printed: May 26 2012

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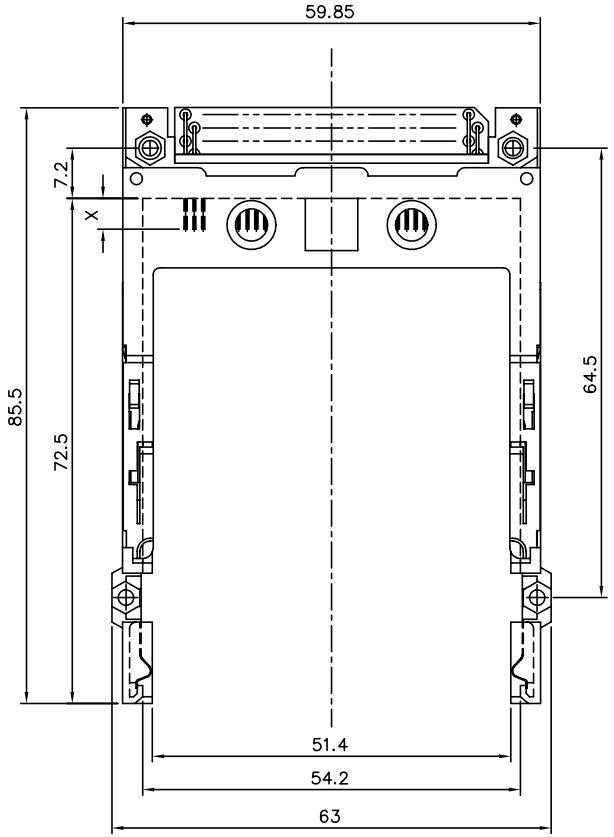
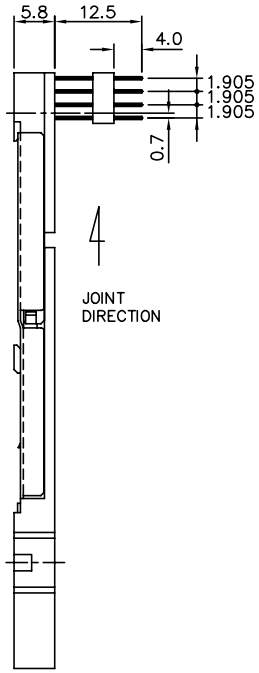
PRODUCT NO.
74500-000
74500-000LF





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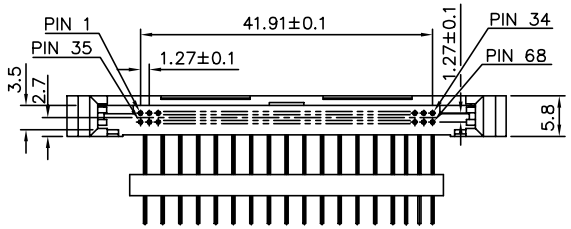

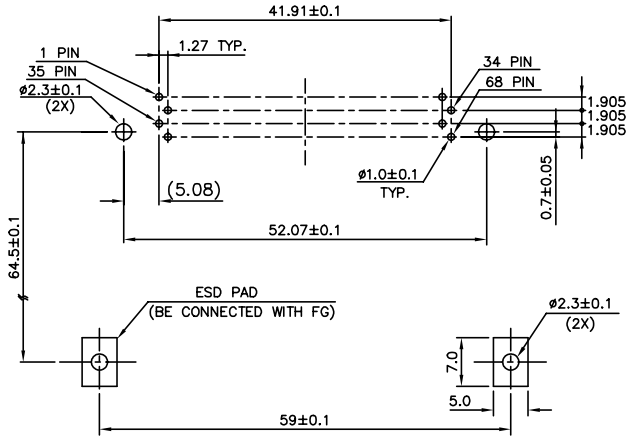

CARD INSERTION DIRECTION

mat'l. code	surface	tolerance	projection	product family
	ISO1302	ISO406 ISO1101		PCMCIA

ltr	ecn	nodr	date
F			

tolerances unless otherwise specified

angle	linear	
		0.X±0.3
		0.XX±0.13
0°±2°		0.XXX±0.05

MM

scale 1.6:1

title: EJECTOR HEADER ASS'Y 68POS. R/A TYP 1/2/3

dr	WENDY.CHEN	07/30/97
engr	JOSPH HSIA	07/30/97
chr	JOSEPH HSIA	07/30/97
appd	JENN TSAO	07/30/97

dwg no 74500 sheet 2 of 2 size A4

type Product Customer Drawing

sheet index | revision sheet

form: A4mmXLc

PDS: Rev :F STATUS:Released Printed: May 26 2012